



MATERIAL DATA FORM

Manufacturer contact Information

Contact Name	Compliance Coordinator
Tel. No.	+1 (805) 377-3648
E-mail address	Compliance@diodes.com

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
DCPxxx	0.112	Die, Transistor	Doped silicon	TBD	0.2405	0.21%	2141
Customer's Partnumber.		SOT-223 leadframe	CDA-194	37507841	64.6356	57.56%	575604
			Die attached pad plating	37507916	0.7875	0.70%	7013
		Bonding wire	Gold	3399000	0.2348	0.21%	2091
		Molding compound	EME-G600	TBD	44.5047	39.63%	396330
		Die attach epoxy	8200TI	TBD	0.1142	0.10%	1017
		Tin solder	Pure Tin	37508652	1.7746	1.58%	15804

Total (mg)	112.292
--------------	---------



MATERIAL DATA FORM DETAIL

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight	
DCPxxx	0.112	Die, Transistor	Doped silicon	Si	7440-21-3	0.2405	100.00%	1000000	2141	
Customer's Partnumber.		SOT-223 leadframe	CDA 194	Cu	7440-50-8	62.9551	97.40%	974000	560638	
				Fe	7439-89-6	1.5513	2.40%	24000	13814	
				P	7723-14-0	0.0517	0.08%	800	460	
				Zn	7440-66-6	0.0776	0.12%	1200	691	
				Pure silver	Ag	7440-22-4	0.7875	100.00%	1000000	7013
			Bonding wire	2.0mil	Au	7440-57-5	0.2348	100.00%	1000000	2091
			Molding compound	EME-G600	Epoxy Resin	-----	2.2252	5.00%	50000	19817
					Phenol Resin	-----	2.2252	5.00%	50000	19817
					Bismuth/Bismuth co	-----	0.0223	0.05%	500	198
					SiO2	60676-86-0	38.9193	87.45%	874500	346591
		Cresol Novolac			29690-82-2	0.8901	2.00%	20000	7927	
				C	1333-86-4	0.2225	0.50%	5000	1982	
		Die attached epoxy	8200TI	Ag	7440-22-4	0.0913	80.00%	800000	813	
				Acrylate resins	Trade secret	0.0228	20.00%	200000	203	
		Tin solder	Pure Tin	Sn	7440-31-5	1.7746	100.00%	1000000	15804	
Total (mg)						112.292				

MATERIALS DISCLOSURE DISCLAIMER

- The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"
- Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.
- These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELVII and RoHS I, RoHS II and reported above:

- | | |
|---|--|
| <ol style="list-style-type: none"> Antimony compounds Asbestos Azo compounds Cadmium and cadmium compounds Certain Shortchain Chlorinated Paraffins Chlorinated organic compounds Halogens Hexavalent chromium compounds Lead and lead compounds Mercury and mercury compounds Organic tin compounds | <ol style="list-style-type: none"> Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) Ozone Depleting Substances - Class II (HCFCs) Perfluorooctane Sulphonate (PFOS) or related compounds Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE Polychlorinated Biphenyls (PCBs) Polychlorinated Naphthalenes (>3 chlorine atoms) Radioactive Substances Tributyl Tin (TBT) and Triphenyl Tin (TPT) Tributyl Tin Oxide (TBTO) |
|---|--|

This product or product family does not contain any chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHCs) under REACH. Please check the document at http://www.diodes.com/files/products_lead_free/RoHS_Product_List.pdf for the current compliance status.